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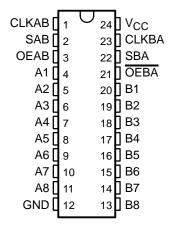
- Bus Transceivers/Registers
- Independent Registers and Enables for A and B Buses
- Multiplexed Real-Time and Stored Data
- Choice of True or Inverting Data Paths
- Choice of 3-State or Open-Collector Outputs to A Bus

DEVICE	A OUTPUT	B OUTPUT	LOGIC
SN74ALS651A, 'AS651	3-State	3-State	Inverting
SN54ALS652, SN74ALS652A, 'AS652	3-State	3-State	True
'ALS653	Open Collector	3-State	Inverting
SN74ALS654	Open Collector	3-State	True

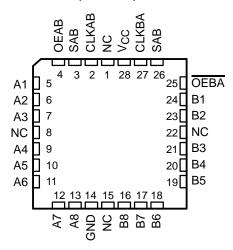
### description

These devices consist of bus-transceiver circuits. D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the data bus or from the internal storage registers. Output-enable (OEAB and OEBA) inputs are provided to control the transceiver functions. Select-control (SAB and SBA) inputs are provided to select real-time or stored data transfer. The circuitry used for select control eliminates the typical decoding glitch that occurs in a multiplexer during the transition between stored and real-time data. A low input level selects real-time data, and a high input level selects stored data. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the octal bus transceivers and registers

SN54ALS', SN54AS' . . . JT PACKAGE SN74ALS', SN74AS' . . . DW OR NT PACKAGE (TOP VIEW)



SN54ALS', SN54AS' . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

Data on the A or B data bus, or both, can be stored in the internal D-type flip-flops by low-to-high transitions at the appropriate clock (CLKAB or CLKBA) terminals, regardless of the select- or output-control terminals. When SAB and SBA are in the real-time transfer mode, it is possible to store data without using the internal D-type flip-flops by simultaneously enabling OEAB and OEBA. In this configuration, each output reinforces its input. When all other data sources to the two sets of bus lines are at high impedance, each set of bus lines remains at its last state.

The -1 versions of the SN74ALS651A and SN74ALS652A are identical to the standard versions except that the recommended maximum  $I_{OL}$  for the -1 versions is increased to 48 mA. There are no -1 versions of the SN54ALS652, SN54ALS653, SN74ALS653, and SN74ALS654.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



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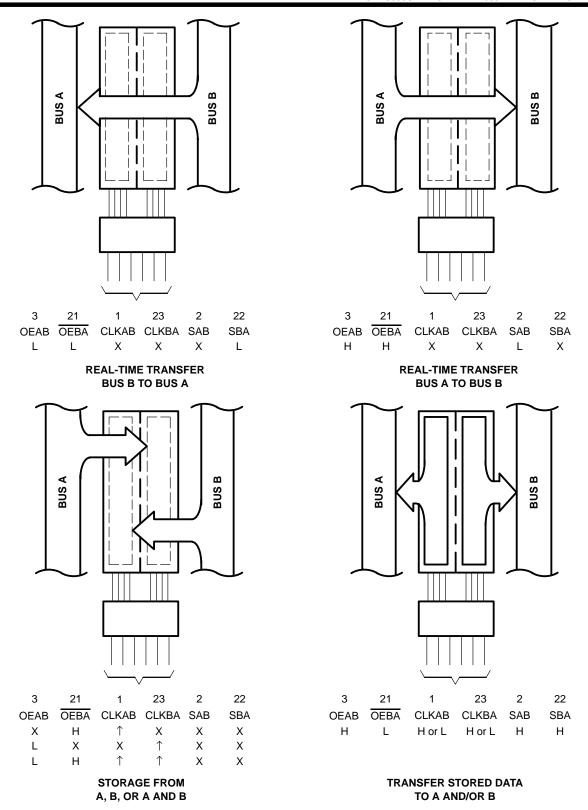
### **ORDERING INFORMATION**

TA	PACK	AGET	ORDERABLE PART NUMBER	TOP-SIDE MARKING
			SN74ALS651ANT	SN74ALS651ANT
			SN74ALS652ANT	SN74ALS652ANT
	PDIP – NT	Tube	SN74ALS653NT	SN74ALS653NT
	PDIP - NT	Tube	SN74ALS654NT	SN74ALS654NT
			SN74AS651NT	SN74AS651NT
			SN74AS652NT	SN74AS652NT
		Tube	SN74ALS651ADW	ALS651A
		Tape and reel	SN74ALS651ADWR	ALSOSTA
0°C to 70°C		Tube	SN74ALS652ADW	ALS652A
0.0 10 70.0		Tape and reel	SN74ALS652ADWR	AL3032A
	SOIC – DW	Tube	SN74ALS653DW	ALS653
		Tape and reel	SN74ALS653DWR	AL3033
		Tube	SN74ALS654DW	ALS654
		Tape and reel	SN74ALS654DWR	AL3034
		Tube	SN74AS651DW	AS651
		Tape and reel	SN74AS651DWR	A3031
		Tube	SN74AS652DW	AS652
		Tape and reel	SN74AS652DWR	A3032
			SNJ54ALS652JT	SNJ54ALS652JT
	CDIP – JT	Tube	SNJ54ALS653JT	SNJ54ALS653JT
	CDIP = 31	Tube	SNJ54AS651JT	SNJ54AS651JT
–55°C to 125°C			SNJ54AS652JT	SNJ54AS652JT
-55 0 10 125 0			SNJ54ALS652FK	SNJ54ALS652FK
	LCCC – FK	Tube	SNJ54ALS653FK	SNJ54ALS653FK
	LCCC - FK	Tube	SNJ54AS651FK	SNJ54AS651FK
			SNJ54AS652FK	SNJ54AS652FK

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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Pin numbers shown are for the DW, JT, and NT packages.

Figure 1. Bus-Management Functions



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#### **Function Tables**

#### SN54ALS653, SN54AS651, SN74ALS651A, SN74ALS653, SN74AS651

		INPU <sup>-</sup>	гѕ			DATA	\ I/O <sup>†</sup>	OPERATION OR FUNCTION
OEAB	OEBA	CLKAB	CLKBA	SAB	SBA	A1-A8	B1-B8	OPERATION OR FUNCTION
L	Н	H or L	H or L	Х	Х	Input	Input	Isolation
L	Н	1	1	X	X	Input	Input	Store A and B data
Х	Н	1	H or L	Х	Х	Input	Unspecified <sup>‡</sup>	Store A, hold B
Н	Н	$\uparrow$	$\uparrow$	X‡	Х	Input	Output	Store A in both registers
L	Х	H or L	1	Х	Х	Unspecified <sup>‡</sup>	Input	Hold A, store B
L	L	$\uparrow$	$\uparrow$	X	X‡	Output	Input	Store B in both registers
L	L	Х	Х	Х	L	Output	Input	Real-time B data to A bus
L	L	Χ	H or L	X	Н	Output	Input	Stored $\overline{B}$ data to A bus
Н	Н	Χ	Х	L	Х	Input	Output	Real-time A data to B bus
Н	Н	H or L	Χ	Н	Х	Input	Output	Stored $\overline{A}$ data to B bus
Н	L	H or L	H or L	Н	Н	Output	Output	Stored A data to B bus and stored B data to A bus

<sup>†</sup> The data output functions can be enabled or disabled by a variety of level combinations at OEAB or OEBA. Data input functions always are enabled; i.e., data at the bus terminals is stored on every low-to-high transition on the clock inputs.

Select control = H: clocks must be staggered to load both registers.

#### SN54ALS652, SN54AS652, SN74ALS652A, SN74ALS654, SN74AS652

		INPU <sup>-</sup>	rs			DATA	\ I/O†	OPERATION OR FUNCTION
OEAB	OEBA	CLKAB	CLKBA	SAB	SBA	A1-A8	B1-B8	OPERATION OR FUNCTION
L	Н	H or L	H or L	Х	Х	Input	Input	Isolation
L	Н	$\uparrow$	1	X	X	Input	Input	Store A and B data
Х	Н	<b>↑</b>	H or L	Х	Х	Input	Unspecified <sup>‡</sup>	Store A, hold B
Н	Н	$\uparrow$	$\uparrow$	X‡	X	Input	Output	Store A in both registers
L	Х	H or L	1	Х	Х	Unspecified <sup>‡</sup>	Input	Hold A, store B
L	L	$\uparrow$	1	Χ	<b>X</b> ‡	Output	Input	Store B in both registers
L	L	Х	Х	Х	L	Output	Input	Real-time B data to A bus
L	L	Χ	H or L	Χ	Н	Output	Input	Stored B data to A bus
Н	Н	Χ	Х	L	Х	Input	Output	Real-time A data to B bus
Н	Н	H or L	Χ	Н	X	Input	Output	Stored A data to B bus
Н	L	H or L	H or L	Н	Н	Output	Output	Stored A data to B bus and stored B data to A bus

<sup>†</sup> The data output functions can be enabled or disabled by a variety of level combinations at OEAB or OEBA. Data input functions always are enabled; i.e., data at the bus terminals is stored on every low-to-high transition on the clock inputs.

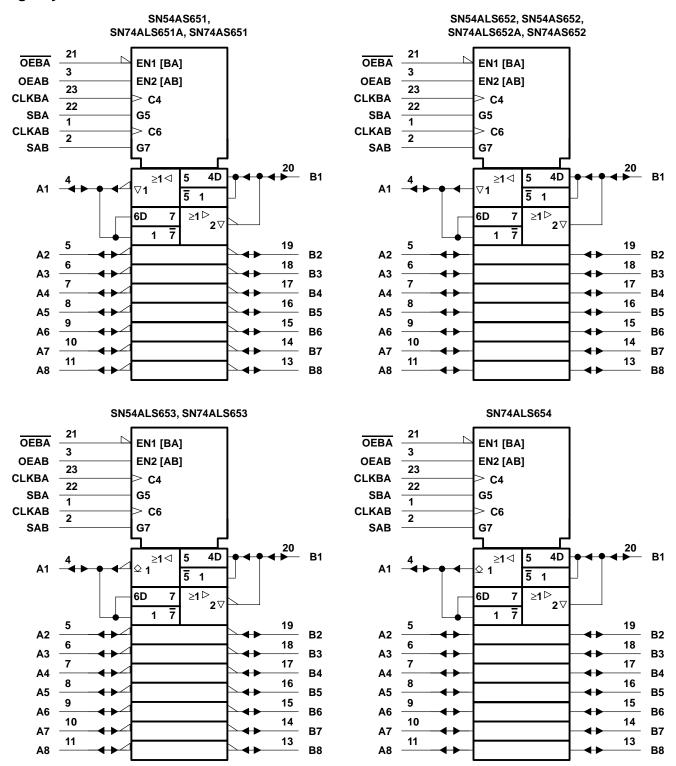
Select control = H: clocks must be staggered to load both registers.



<sup>‡</sup> Select control = L: clocks can occur simultaneously.

<sup>‡</sup> Select control = L: clocks can occur simultaneously.

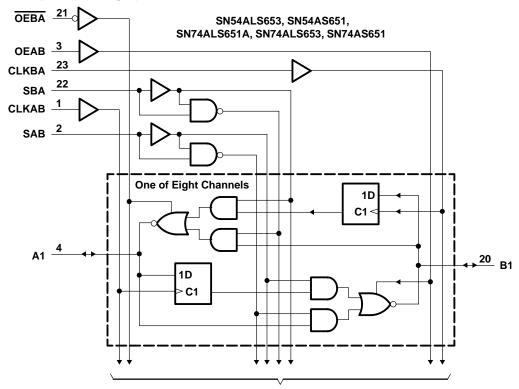
### logic symbols†



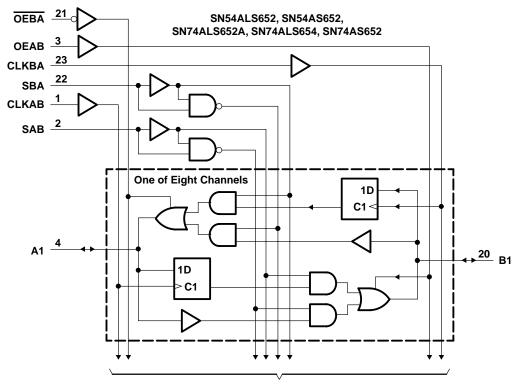
<sup>†</sup> These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DW, JT, and NT packages.



### logic diagrams (positive logic)



To Seven Other Channels



To Seven Other Channels

Pin numbers shown are for the DW, JT, and NT packages.



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## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	-0.5 V to 7 V
Input voltage range, V <sub>I</sub> : Control inputs	
I/O ports	–0.5 V to 5.5 V
Package thermal impedance, θ <sub>JA</sub> (see Note 1): DW package	46°C/W
NT package	67°C/W
Storage temperature range, T <sub>sto</sub>	65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### recommended operating conditions

			SN74ALS651A		UNIT	
			MIN	NOM	MAX	UNII
Vсс	Supply voltage		4.5	5	5.5	V
VIH	High-level input voltage		2			V
V <sub>IL</sub>	Low-level input voltage				0.8	V
loh	High-level output current				-15	mA
Landard comment					24	A
lOL	DL Low-level output current				48‡	mA
fclock	Clock frequency		0		40	MHz
	Pulse duration	CLKBA or CLKAB high	12.5			no
t <sub>W</sub>	Pulse duration	CLKBA or CLKAB low	12.5			ns
t <sub>su</sub>	Setup time before CLKAB↑ or CLKBA↑	A or B	10			ns
t <sub>h</sub>	Hold time after CLKAB↑ or CLKBA↑	A or B	0			ns
TA	Operating free-air temperature		0		70	°C

<sup>‡</sup> Applies only to the SN74ALS651A-1 and only if V<sub>CC</sub> is maintained between 4.75 V and 5.25 V

### recommended operating conditions

			SN54ALS652		52	SN7	4ALS65	2A	LINUT	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Vсс	Supply voltage		4.5	5	5.5	4.5	5	5.5	V	
VIH	High-level input voltage		2			2			V	
VIL	Low-level input voltage				0.7			0.8	V	
IOH	High-level output current				-12			-15	mA	
					12			24	mA	
lOL	Low-level output current							48‡		
fclock	Clock frequency		0		35	0		40	MHz	
	Pulse duration	CLKBA or CLKAB high	14.5			12.5				
t <sub>W</sub>	Pulse duration	CLKBA or CLKAB low	14.5			12.5			ns	
t <sub>su</sub>	Setup time before CLKAB↑ or CLKBA↑	A or B	15			10			ns	
th	Hold time after CLKAB↑ or CLKBA↑	A or B	5			0			ns	
TA	Operating free-air temperature		-55		125	0		70	°C	

 $<sup>\</sup>ddagger$  Applies only to the SN74ALS652A-1 and only if V<sub>CC</sub> is maintained between 4.75 V and 5.25 V



NOTE 1: The package thermal impedance is calculated in accordance with JESD 51.

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# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	DADAMETED	TEOT 0	ONDITIONS	SN7	74ALS65	1A	LINUT
	PARAMETER	IESI C	ONDITIONS	MIN	TYP <sup>†</sup>	MAX	UNIT
٧ıĸ		V <sub>CC</sub> = 4.5 V,	I <sub>I</sub> = –18 mA			-1.2	V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	VCC-	2		
Vон		V <sub>CC</sub> = 4.5 V	$I_{OH} = -3 \text{ mA}$	2.4	3.2		V
		VCC = 4.5 V	$I_{OH} = -15 \text{ mA}$	2			
		V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 12 mA		0.25	0.4	
VOL		VCC = 4.5 V	I <sub>OL</sub> = 24 mA		0.35	0.5	V
		$V_{CC} = 4.75 \text{ V},$	I <sub>OL</sub> = 48 mA (-1 versions)		0.35	0.5	
١.	Control inputs	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 7 V			0.1	mA
ŧι	A or B ports	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 5.5 V			0.1	IIIA
1	Control inputs		V 07V			20	
IН	A or B ports‡	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 2.7 V			20	μΑ
	Control inputs	V 55V	V 0.4V			-0.2	4
l IIL	A or B ports‡	V <sub>CC</sub> = 5.5 V,	$V_{  } = 0.4 V$			-0.2	mA
IO§	-	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.25 V	-30		-112	mA
			Outputs high		42	68	
<sup>I</sup> CC		V <sub>CC</sub> = 5.5 V	Outputs low		52	82	mA
			Outputs disabled		52	82	

<sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

<sup>‡</sup> For I/O ports, the parameters I<sub>IH</sub> and I<sub>IL</sub> include the off-state output current.

<sup>§</sup> The output conditions have been chosen to produce a current that closely approximates one-half of the true short-circuit output current, IOS.

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# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	DAMETER	TECT	CONDITIONS	SN	54ALS6	52	SN74ALS652A			LINIT
PA	RAMETER	1531	CONDITIONS	MIN	TYP <sup>†</sup>	MAX	MIN	TYP <sup>†</sup>	MAX	UNIT
٧ıK		$V_{CC} = 4.5 \text{ V},$	$I_1 = -18 \text{ mA}$			-1.2			-1.2	V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	V <sub>CC</sub> -2			V <sub>CC</sub> -2			
\/a			$I_{OH} = -3 \text{ mA}$	2.4	3.2		2.4	3.2		V
VOH		V <sub>CC</sub> = 4.5 V	$I_{OH} = -12 \text{ mA}$	2						V
			I <sub>OH</sub> = -15 mA				2			
		V 45V	I <sub>OL</sub> = 12 mA		0.25	0.4		0.25	0.4	
VOL	V <sub>CC</sub> = 4.5 V		I <sub>OL</sub> = 24 mA					0.35	0.5	V
		V <sub>CC</sub> = 4.75 V,	I <sub>OL</sub> = 48 mA (-1 versions)					0.35	0.5	
Ī	Control inputs	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 7 V			0.1			0.1	mA
l II	A or B ports	$V_{CC} = 5.5 \text{ V},$	V <sub>I</sub> = 5.5 V			0.1			0.1	IIIA
	Control inputs	V 55V	V 07V			20			20	•
ΙН	A or B ports‡	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 2.7 V			20			20	μΑ
	Control inputs	.,,				-0.2			-0.2	
lı∟	A or B ports‡	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 0.4 V			-0.2			-0.2	mA
ΙΟ§		V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.25 V	-20		-112	-30		-112	mA
			Outputs high		47	76		47	76	
ICC		V <sub>CC</sub> = 5.5 V	Outputs low		55	88		55	88	mA
			Outputs disabled		55	88		55	88	

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

<sup>‡</sup> For I/O ports, the parameters I<sub>IH</sub> and I<sub>IL</sub> include the off-state output current.

<sup>§</sup> The output conditions have been chosen to produce a current that closely approximates one-half of the true short-circuit output current, IOS.

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PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 4.5 C <sub>L</sub> = 50 pF R1 = 500 Ω R2 = 500 Ω T <sub>A</sub> = MIN t	;, <u>)</u> , <u>)</u> ,	UNIT
			MIN	MAX	
f <sub>max</sub>			40		MHz
<sup>t</sup> PLH	CLKBA or CLKAB	A or B	8	32	ns
<sup>t</sup> PHL	CENDA OF CENAD	AGIB	5	17	113
<sup>t</sup> PLH	A or B	B or A	2	18	ns
<sup>t</sup> PHL	A 01 B	B 01 A	2	10	113
<sup>t</sup> PLH	SBA or SAB‡	A or B	8	38	ns
<sup>t</sup> PHL	(with A or B high)	AOIB	6	21	
<sup>t</sup> PLH	SBA or SAB‡	A or B	8	25	ns
<sup>t</sup> PHL	(with A or B low)	AOIB	7	21	115
<sup>t</sup> PZH		А	3	20	no
<sup>t</sup> PZL	OEBA	A	5	18	ns
<sup>t</sup> PHZ		А	2	9	
<sup>t</sup> PLZ	OEBA	A	3	12	ns
<sup>t</sup> PZH	OEAB	В	3	22	
<sup>t</sup> PZL	DEAD	В	6	21	ns
t <sub>PHZ</sub>	OEAB		2	12	ns
<sup>t</sup> PLZ	OEAB	В	2	14	

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



<sup>‡</sup> These parameters are measured with the internal output state of the storage register opposite that of the bus input.

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PARAMETER	FROM (INPUT)	TO (OUTPUT)	V, C R R T,	UNIT			
			SN54A	LS652	SN74AL	S652A	
			MIN	MAX	MIN	MAX	
f <sub>max</sub>			35		40		MHz
<sup>t</sup> PLH	CLKBA or CLKAB	A or B	10	35	8	30	ns
<sup>t</sup> PHL	CENDA OF CENAD	AOIB	5	20	5	17	115
<sup>t</sup> PLH	A or B	B or A	5	20	4	18	ns
<sup>t</sup> PHL	AOID	BULK	3	15	3	12	113
<sup>t</sup> PLH	SBA or SAB‡	A or B	15	40	8	35	ns
<sup>t</sup> PHL	(with A or B high)	A 01 B	6	23	6	20	113
<sup>t</sup> PLH	SBA or SAB‡	A or B	8	30	8	25	ns
<sup>t</sup> PHL	(with A or B low)	AOIB	5	24	5	20	115
<sup>t</sup> PZH		A	3	20	3	17	ns
<sup>t</sup> PZL	OEBA		5	22	5	18	115
<sup>t</sup> PHZ		A	1	12	1	10	ns
<sup>t</sup> PLZ	<u>OEBA</u>	^	2	20	2	16	115
<sup>t</sup> PZH	OEAB	В	8	25	3	22	ns
t <sub>PZL</sub>	UEAD	D	6	21	5	18	115
<sup>t</sup> PHZ	OEAB	В	1	12	1	10	ns
<sup>t</sup> PLZ	OLAB		2	21	2	16	115

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

<sup>&</sup>lt;sup>‡</sup> These parameters are measured with the internal output state of the storage register opposite that of the bus input.

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### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V <sub>CC</sub>	–0.5 V to 7 V
Input voltage range, V <sub>I</sub> : Control inputs	–0.5 V to 7 V
I/O ports	–0.5 V to 5.5 V
Package thermal impedance, θ <sub>JA</sub> (see Note 1): DW package	46°C/W
NT package	67°C/W
Storage temperature range, T <sub>sto</sub>	. –65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### recommended operating conditions

			SN	54ALS6	53	SN	74ALS6	53	UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	UNII
Vсс	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage		2			2			V
V <sub>IL</sub>	Low-level input voltage				0.7			0.8	V
Vон	High-level output voltage	A ports			5.5			5.5	V
ЮН	High-level output current	B ports			-12			-15	mA
l <sub>OL</sub>	Low-level output current				12			24	mA
f <sub>clock</sub>	Clock frequency		0		25	0		35	MHz
	Pulse duration	CLKBA or CLKAB high	20			14.5			20
t <sub>W</sub>	ruise dulation	CLKBA or CLKAB low	20			14.5			ns
t <sub>su</sub>	Setup time before CLKAB↑ or CLKBA↑	A or B	15			10			ns
t <sub>h</sub>	Hold time after CLKAB↑ or CLKBA↑	A or B	5			0			ns
TA	Operating free-air temperature		-55		125	0		70	°C

### recommended operating conditions

			SN	74ALS6	54	LINUT
			MIN	NOM	MAX	UNIT
Vcc	Supply voltage		4.5	5	5.5	V
$V_{IH}$	High-level input voltage		2			V
V <sub>I</sub> L	Low-level input voltage				0.8	V
Vон	High-level output voltage	A ports			5.5	V
lOH	High-level output current	B ports			-15	mA
lOL	Low-level output current				24	mA
fclock	Clock frequency		0		35	MHz
	Pulse duration	CLKBA or CLKAB high	14.5			20
t <sub>W</sub>	ruise duration	CLKBA or CLKAB low	14.5			ns
t <sub>su</sub>	Setup time before CLKAB↑ or CLKBA↑	A or B	10			ns
th	Hold time after CLKAB↑ or CLKBA↑	A or B	0			ns
TA	Operating free-air temperature		0		70	°C



NOTE 1: The package thermal impedance is calculated in accordance with JESD 51.

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# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	DAMETER	TEOT	CONDITIONS	SN	54ALS6	53	SN7	74ALS6	53	UNIT
P#	ARAMETER	1551	CONDITIONS	MIN	TYP <sup>†</sup>	MAX	MIN	TYP <sup>†</sup>	MAX	UNII
٧ıK		$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$			-1.2			-1.2	V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	V <sub>CC</sub> -2			V <sub>CC</sub> -2			
V	B ports		$I_{OH} = -3 \text{ mA}$	2.4	3.2		2.4	3.2		V
VOH	b ports	V <sub>CC</sub> = 4.5 V	$I_{OH} = -12 \text{ mA}$	2						V
			I <sub>OH</sub> = -15 mA				2			
Voi		V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 12 mA		0.25	0.4		0.25	0.4	V
VOL		VCC = 4.5 V	I <sub>OL</sub> = 24 mA					0.35	0.5	V
1.	Control inputs	$V_{CC} = 5.5 \text{ V},$	V <sub>I</sub> = 7 V			0.1			0.1	mA
l <sub>l</sub>	A or B ports	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 5.5 V			0.1			0.1	IIIA
	Control inputs	V 55V	V 07V			20			20	•
lн	A or B ports‡	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 2.7 V			20			20	μΑ
	Control inputs	v 55V	V 04V			-0.2			-0.2	•
lIL.	A or B ports‡	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 0.4 V			-0.2			-0.2	mA
loh	A ports	V <sub>CC</sub> = 4.5 V,	V <sub>OH</sub> = 5.5 V			0.1			0.1	mA
ΙΟ§	B ports	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.25 V	-20		-112	-30		-112	mA
	-		Outputs high		47	76		47	76	
ICC		V <sub>CC</sub> = 5.5 V	Outputs low		55	88		55	88	mA
			Outputs disabled		55	88		55	88	

 $<sup>\</sup>uparrow$  All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

<sup>‡</sup> For I/O ports, the parameters I<sub>IH</sub> and I<sub>IL</sub> include the off-state output current.

<sup>§</sup> The output conditions have been chosen to produce a current that closely approximates one-half of the true short-circuit output current, IOS.

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# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	DADAMETED	TEOT 001	IDITIONS	SN	74ALS6	54	UNIT
	PARAMETER	TEST CON	DITIONS	MIN	TYP <sup>†</sup>	MAX	UNII
VIK		V <sub>CC</sub> = 4.5 V,	I <sub>I</sub> = -18 mA			-1.2	V
		V <sub>CC</sub> = 4.5 V to 5.5 V,	$I_{OH} = -0.4 \text{ mA}$	V <sub>CC</sub> -2			
Vон	B ports	V <sub>CC</sub> = 4.5 V	$I_{OH} = -3 \text{ mA}$	2.4	3.2		V
		VCC = 4.5 V	$I_{OH} = -15 \text{ mA}$	2			
VOL		V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 12 mA		0.25	0.4	V
VOL		VCC = 4.5 V	I <sub>OL</sub> = 24 mA		0.35	0.5	V
1.	Control inputs	$V_{CC} = 5.5 \text{ V},$	V <sub>I</sub> = 7 V			0.1	mA
li l	A or B ports	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 5.5 V			0.1	ША
1	Control inputs	V 5.5.V	V: 27V			20	
lін	A or B ports‡	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 2.7 V			20	μΑ
1	Control inputs	V 55V	V <sub>2</sub> 0.4.V			-0.2	A
¹ı∟	A or B ports‡	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 0.4 V			-0.2	mA
loн	A ports	V <sub>CC</sub> = 4.5 V,	V <sub>OH</sub> = 5.5 V			0.1	mA
I <sub>O</sub> §	B ports	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.25 V	-30		-112	mA
			Outputs high		47	76	
ICC		V <sub>CC</sub> = 5.5 V	Outputs low		55	88	mA
			Outputs disabled		55	88	

<sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

<sup>‡</sup> For I/O ports, the parameters I<sub>IH</sub> and I<sub>IL</sub> include the off-state output current.

<sup>§</sup> The output conditions have been chosen to produce a current that closely approximates one-half of the true short-circuit output current, IOS.

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PARAMETER	FROM (INPUT)	то (оитрит)	C <sub>L</sub> = 50 R <sub>L</sub> = 68 R1 = R2	$V_{CC}$ = 4.5 V to 5.5 V, $C_L$ = 50 pF, $R_L$ = 680 $\Omega$ (A outputs), $R1$ = $R2$ = 500 $\Omega$ (B outputs), $T_A$ = MIN to MAX $^{\dagger}$					
			SN54A	LS653	SN74A	LS653			
			MIN	MAX	MIN	MAX			
f <sub>max</sub>			25		35		MHz		
<sup>t</sup> PLH	CLKBA	А	16	71	16	64	ns		
<sup>t</sup> PHL	CENBA	Α	6	24	6	22	115		
<sup>t</sup> PLH	CLKAB	В	10	35	10	30	ns		
<sup>t</sup> PHL	CENAB	В	5	20	5	17	115		
<sup>t</sup> PLH	A	В	5	20	5	18	ns		
<sup>t</sup> PHL		В	1.5	18	2	15	115		
<sup>t</sup> PLH	В	A	8	63	12	56	no		
<sup>t</sup> PHL	В	A	2	18	2	15	ns		
<sup>t</sup> PLH	SBA <sup>‡</sup>	А	12	68	19	62	ns		
<sup>t</sup> PHL	(with B high)	۸	5	27	5	25	115		
<sup>t</sup> PLH	SBA <sup>‡</sup>	А	12	68	19	62	ns		
t <sub>PHL</sub>	(with B low)	۸	5	27	5	25	115		
<sup>t</sup> PLH	SAB <sup>‡</sup>	В	8	30	15	35	ns		
t <sub>PHL</sub>	(with A high)	В	6	25	6	22	115		
<sup>t</sup> PLH	SAB <sup>‡</sup>	В	12	40	8	25	ns		
t <sub>PHL</sub>	(with A low)	D	6	25	6	22	115		
<sup>t</sup> PLH	OFDA	А	6	35	6	30	ns		
<sup>t</sup> PHL	<u>OEBA</u>	^	6	27	6	24	115		
<sup>t</sup> PZH	OEAB	В	7	25	8	22	ns		
<sup>t</sup> PZL	OLAD		6	25	6	22	115		
<sup>t</sup> PHZ	OEAB	В	1	16	1	14	nc		
<sup>t</sup> PLZ	) VEAB	D	2	21	2	16	ns		

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

<sup>&</sup>lt;sup>‡</sup> These parameters are measured with the internal output state of the storage register opposite that of the bus input.

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PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC}$ = 4.5 V to 5.5 V, $C_L$ = 50 pF, $R_L$ = 680 $\Omega$ (A outputs), $R1$ = $R2$ = 500 $\Omega$ (B outputs), $T_A$ = MIN to MAX $^{\dagger}$	UNIT
			SN74ALS654	
			MIN MAX	
f <sub>max</sub>			35	MHz
<sup>t</sup> PLH	CLKBA	Α	16 64	ns
<sup>t</sup> PHL	OLNDA	Λ	6 22	113
<sup>t</sup> PLH	CLKAB	В	10 30	ns
<sup>t</sup> PHL	CLIAB	D	5 17	113
<sup>t</sup> PLH	A	В	5 18	ns
t <sub>PHL</sub>	^	ь	2 15	115
<sup>t</sup> PLH	В	А	12 56	
<sup>t</sup> PHL	Ь	A	2 21	ns
<sup>t</sup> PLH	SBA <sup>‡</sup>	Α	19 62	ns
<sup>t</sup> PHL	(with B low)	Α	5 25	115
<sup>t</sup> PLH	SBA <sup>‡</sup>	A	19 62	
<sup>t</sup> PHL	(with B high)	A	5 25	ns
<sup>t</sup> PLH	SAB <sup>‡</sup>	В	15 35	
<sup>t</sup> PHL	(with A low)	D	6 22	ns
<sup>t</sup> PLH	SAB‡	D	8 25	
<sup>t</sup> PHL	(with A high)	В	6 22	ns
<sup>t</sup> PLH		۸	6 30	
<sup>t</sup> PHL	OEBA	Α	6 24	ns
<sup>t</sup> PZH	OFAR	D	6 22	
<sup>t</sup> PZL	OEAB	В	6 22	ns
<sup>t</sup> PHZ	OE A D	D	1 14	
<sup>t</sup> PLZ	OEAB	В	2 16	ns

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

<sup>&</sup>lt;sup>‡</sup> These parameters are measured with the internal output state of the storage register opposite that of the bus input.

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## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	$\dots$ –0.5 V to 7 V
Input voltage range, V <sub>I</sub> : Control inputs	$-0.5$ V to 7 V
I/O ports	$\dots$ -0.5 V to 5.5 V
Package thermal impedance, θ <sub>JA</sub> (see Note 1): DW package	46°C/W
NT package	67°C/W
Storage temperature range, T <sub>stq</sub>	. −65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### recommended operating conditions

				N54AS65 N54AS65		_	N74AS65 N74AS65		UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
Vcc	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage		2			2			V
V <sub>IL</sub>	Low-level input voltage				0.8			0.8	V
ІОН	High-level output current				-12			-15	mA
loL	Low-level output current				32			48	mA
f <sub>clock</sub>	Clock frequency		0*		75*	0		90	MHz
	Pulse duration	CLKBA or CLKAB high	6*			5			
t <sub>W</sub>	Pulse duration	CLKBA or CLKAB low	7*			6			ns
t <sub>su</sub>	Setup time before CLKAB↑ or CLKBA↑	A or B	7*			6			ns
t <sub>h</sub>	Hold time after CLKAB↑ or CLKBA	A or B	0*			0			ns
TA	Operating free-air temperature		-55		125	0		70	°C

<sup>\*</sup> On products compliant to MIL-PRF-38535, this parameter is based on characterized data but is not production tested.



NOTE 1: The package thermal impedance is calculated in accordance with JESD 51.

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# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PA	RAMETER	TEST C	ONDITIONS		N54AS65 N54AS65	-		174AS65 174AS65		UNIT
				MIN	TYP <sup>†</sup>	MAX	MIN	TYP <sup>†</sup>	MAX	
VIK		V <sub>CC</sub> = 4.5 V,	$I_{I} = -18 \text{ mA}$			-1.2			-1.2	V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -2 \text{ mA}$	V <sub>CC</sub> -2			V <sub>CC</sub> -2			
VOH			$I_{OH} = -3 \text{ mA}$	2.4	3.2		2.4	3.2		V
VOH		V <sub>CC</sub> = 4.5 V	$I_{OH} = -12 \text{ mA}$	2						V
			$I_{OH} = -15 \text{ mA}$				2			
V/01		V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 32 mA		0.25	0.5				V
VOL		VCC = 4.5 V	I <sub>OL</sub> = 48 mA					0.35	0.5	V
1.	Control inputs	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 7 V			0.1			0.1	mA
li l	A or B ports	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 5.5 V			0.1			0.1	IIIA
	Control inputs	V 55V	V 07V			20			20	•
Iн	A or B ports‡	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 2.7 V			70			70	μΑ
	Control input	v 55V				-0.5			-0.5	
¹ı∟	A or B ports‡	$V_{CC} = 5.5 \text{ V},$	V <sub>I</sub> = 0.4 V			-0.75			-0.75	mA
IO§		V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.25 V	-30		-112	-30		-112	mA
			Outputs high		110	185		110	185	
	′AS651	V <sub>CC</sub> = 5.5 V	Outputs low		120	195		120	195	
100			Outputs disabled		130	195		130	195	mΑ
Icc			Outputs high		120	195		120	195	IIIA
	'AS652	V <sub>CC</sub> = 5.5 V	Outputs low		130	211		130	211	
			Outputs disabled		130	211		130	211	

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC}$  = 5 V,  $T_A$  = 25 °C.

<sup>‡</sup> For I/O ports, the parameters I<sub>IH</sub> and I<sub>IL</sub> include the off-state output current.

<sup>§</sup> The output conditions have been chosen to produce a current that closely approximates one-half of the true short-circuit output current, los.

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PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>C</sub> C <sub>L</sub> R1 R2 T <sub>A</sub>	UNIT			
			SN54A	\S651	SN74A	S651	
			MIN	MAX	MIN	MAX	
f <sub>max</sub>			75*		90		MHz
<sup>t</sup> PLH	CLKBA or CLKAB	A or B	2	11	2	8.5	ns
<sup>t</sup> PHL	CENDA OF CENAD	AUD	2	10	2	9	113
<sup>t</sup> PLH	A or B	B or A	2	12	2	8	ns
<sup>t</sup> PHL	Au	DOIA	1	8	1	7	113
<sup>t</sup> PLH	SBA or SAB‡	A or B	2	15	2	11	ns
<sup>t</sup> PHL	SBA UI SAB+	A 01 B	2	11	2	9	113
<sup>t</sup> PZH	<del>OEBA</del>	А	2	11	2	10	ns
t <sub>PZL</sub>	OEBA	7	3	18	3	16	113
<sup>t</sup> PHZ	<del></del> OEBA	А	2	10	2	9	ns
<sup>t</sup> PLZ	OEBA	۸	2	10	2	9	113
<sup>t</sup> PZH	OEAB	В	3	12	3	11	ns
t <sub>PZL</sub>	OLAD	U	3	20	3	16	110
<sup>t</sup> PHZ	OEAB	В	2	11	2	10	ns
<sup>t</sup> PLZ	OLAD	ь	2	12	2	11	110

<sup>\*</sup> On products compliant to MIL-PRF-38535, this parameter is based on characterized data but is not production tested.

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

<sup>‡</sup> These parameters are measured with the internal output state of the storage register opposite that of the bus input.

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PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>C</sub>	UNIT			
			SN54A	NS652	SN74A	S652	
			MIN	MAX	TYP	MAX	
f <sub>max</sub>			75*		90		MHz
<sup>t</sup> PLH	CLKBA or CLKAB	A or B	2	11	2	8.5	ns
<sup>t</sup> PHL	CENDA OF CENAD	AOIB	2	10	2	9	115
<sup>t</sup> PLH	A or B	B or A	2	12	2	9	ns
<sup>t</sup> PHL	A or B	DOIA	1	8	1	7	115
t <sub>PLH</sub>	SBA or SAB‡	A or B	2	15	2	11	ns
<sup>t</sup> PHL	SBA UI SAB+	AOID	2	11	2	9	115
<sup>t</sup> PZH	<del>OEBA</del>	Α	2	11	2	10	ns
t <sub>PZL</sub>	OEBA		3	18	3	16	115
<sup>t</sup> PHZ	<del></del> OEBA	A	2	10	2	9	ns
<sup>t</sup> PLZ	OEBA	^	2	10	2	9	115
<sup>t</sup> PZH	OEAB	В	3	12	3	11	ns
t <sub>PZL</sub>	OLAD	<u> </u>	3	20	3	16	110
<sup>t</sup> PHZ	OEAB	В	2	11	2	10	ns
<sup>t</sup> PLZ	OLAB	Ь	2	12	2	11	115

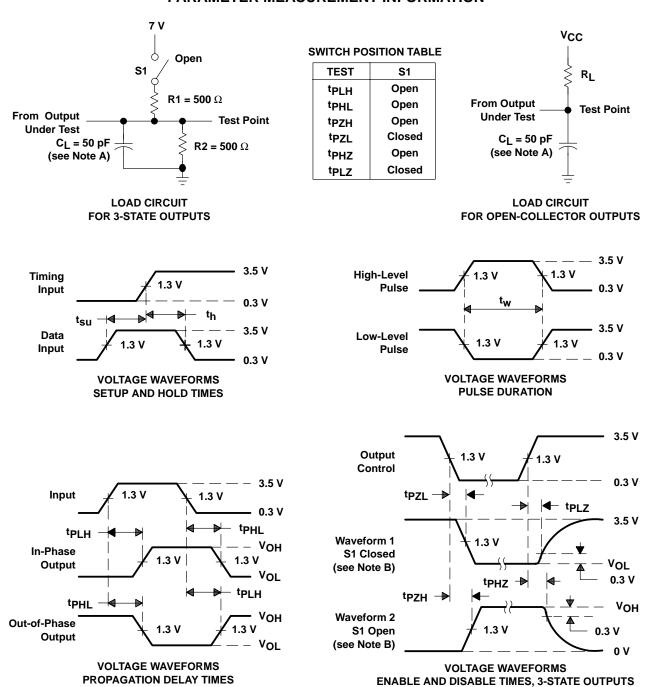
<sup>\*</sup> On products compliant to MIL-PRF-38535, this parameter is based on characterized data but is not production tested.

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

<sup>‡</sup> These parameters are measured with the internal output state of the storage register opposite that of the bus input.

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### PARAMETER MEASUREMENT INFORMATION



NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_0 = 50 \Omega$ ,  $t_f \leq$  2 ns.  $t_f \leq$  2 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 2. Load Circuits and Voltage Waveforms







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### **PACKAGING INFORMATION**

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-88673013A	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 88673013A SNJ54ALS 652FK	Samples
5962-8867301LA	ACTIVE	CDIP	JT	24	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8867301LA SNJ54ALS652JT	Samples
5962-8868701LA	ACTIVE	CDIP	JT	24	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8868701LA SNJ54AS652JT	Samples
5962-89687013A	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 89687013A SNJ54ALS 653FK	Samples
5962-8968701LA	ACTIVE	CDIP	JT	24	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8968701LA SNJ54ALS653JT	Samples
SN54ALS652JT	ACTIVE	CDIP	JT	24	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54ALS652JT	Samples
SN54AS652JT	ACTIVE	CDIP	JT	24	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54AS652JT	Samples
SN74ALS652A-1DW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS652A-1	Samples
N74ALS652A-1DWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS652A-1	Samples
SN74ALS652ADW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS652A	Samples
SN74ALS652ADWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS652A	Samples
SN74ALS652ADWRE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS652A	Samples
SN74ALS653DW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS653	Samples
SN74ALS653DWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS653	Samples
SN74ALS653DWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS653	Samples
SN74ALS654DW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS654	Samples



### PACKAGE OPTION ADDENDUM

17-Mar-2017

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SN74ALS654DWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS654	Samples
SN74AS652DW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	AS652	Samples
SNJ54ALS652FK	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 88673013A SNJ54ALS 652FK	Samples
SNJ54ALS652JT	ACTIVE	CDIP	JT	24	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8867301LA SNJ54ALS652JT	Samples
SNJ54ALS653FK	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 89687013A SNJ54ALS 653FK	Samples
SNJ54ALS653JT	ACTIVE	CDIP	JT	24	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8968701LA SNJ54ALS653JT	Samples
SNJ54AS652JT	ACTIVE	CDIP	JT	24	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8868701LA SNJ54AS652JT	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



### PACKAGE OPTION ADDENDUM

17-Mar-2017

- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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#### OTHER QUALIFIED VERSIONS OF SN54ALS653, SN54AS652, SN74ALS653, SN74AS652:

Catalog: SN74ALS653, SN74AS652

Military: SN54ALS653, SN54AS652

NOTE: Qualified Version Definitions:

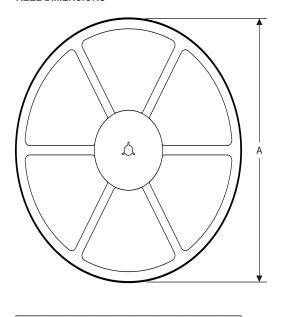
- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

# PACKAGE MATERIALS INFORMATION

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### TAPE AND REEL INFORMATION

### **REEL DIMENSIONS**



### **TAPE DIMENSIONS**



A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

### TAPE AND REEL INFORMATION

\*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS652ADWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1
SN74ALS653DWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1
SN74ALS654DWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

**PACKAGE MATERIALS INFORMATION** 

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\*All dimensions are nominal

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Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
SN74ALS652ADWR	SOIC	DW	24	2000	367.0	367.0	45.0	
SN74ALS653DWR	SOIC	DW	24	2000	367.0	367.0	45.0	
SN74ALS654DWR	SOIC	DW	24	2000	367.0	367.0	45.0	

### JT (R-GDIP-T\*\*)

#### 24 LEADS SHOWN

### **CERAMIC DUAL-IN-LINE**



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP3-T24, GDIP4-T28, and JEDEC MO-058 AA, MO-058 AB

# FK (S-CQCC-N\*\*)

# LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



DW (R-PDSO-G24)

# PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



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